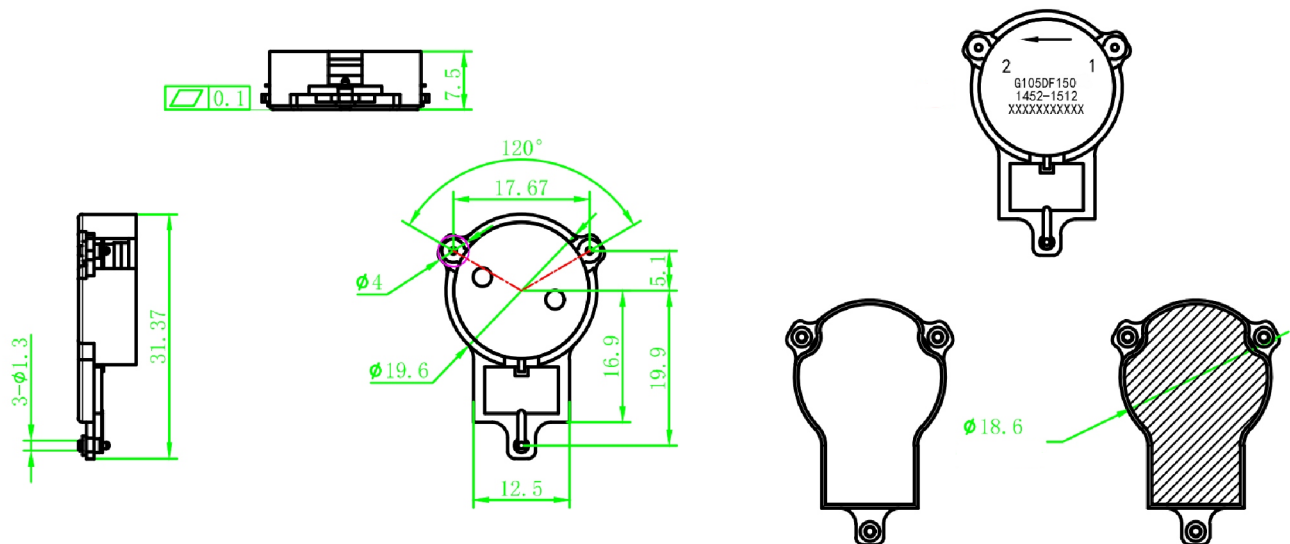


1.Features

UMTS, LTE Band
 PCB Soldering Re-flow
 Wide Operation Temperature Range -45 ~ 125°C
 Compact Package Design for PCB Applications

2.Dimensions

Unit:mm



3.Specifications

Part No.	Frequency (GHz)		Center Frequency	Bandwidth	Isolation	INS LOSS	VSWR	Power	IMD (@2X43dBm)
	F1	F2	(GHz)	(GHz)	(dB) MIN	(dB) MAX	(dB) MAX	(W)	(-dBc) MAX
G105DF150-30(791-821)MHz	0.721	0.821	0.7710	0.100	23	0.25	1.19	150	-72
G105DZ150-30(851-894)MHz	0.851	0.894	0.8725	0.043	23	0.25	1.15	150	-70
G105DF150-30(925-960)MHz	0.925	0.960	0.9425	0.035	25	0.35	1.15	150	-72
G105DZ150-30(1805-1880)MHz	1.805	1.880	1.8425	0.075	28	0.15	1.12	150	-72
G105DZ150-30(2110-2170)MHz	2.110	2.170	2.1400	0.060	25	0.2	1.12	150	-76
G105DF150-30(2600-2720)MHz	2.600	2.720	2.6600	0.120	28	0.15	1.12	150	-72